

查询56-G6005-001供应商

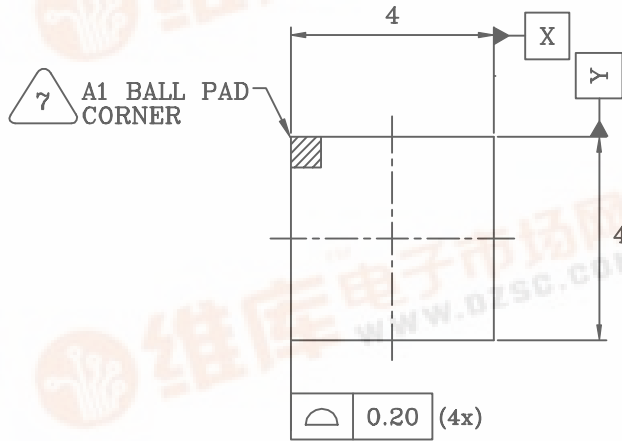
REVISIONS

LTR.	DATE	APPROVED
A	3/00	

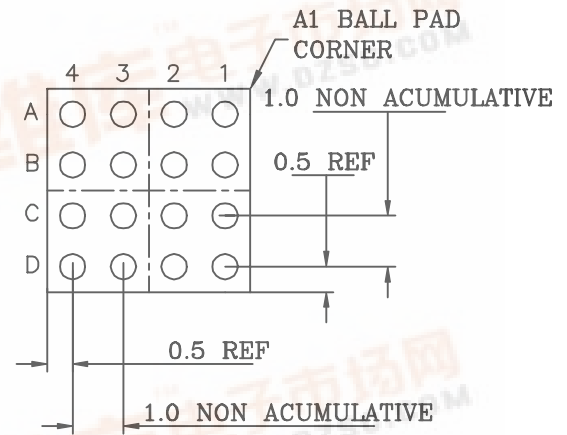
捷多邦, 专业PCB打样工厂, 24小时加急出货

NEW DRAWING

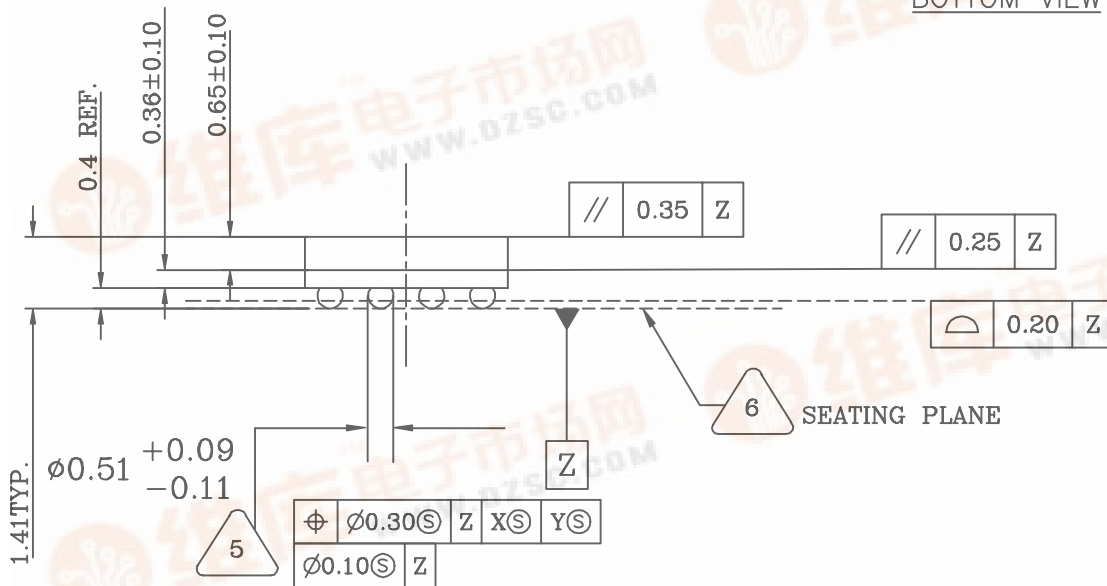
3/00



TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS
2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
3. SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
4. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
7. A1 BALL PAD CORNER I.D. IS IDENTIFIED BY LASER MARKED DOT AT THE CORNER.

SIGNATURE

DATE



Dallas Semiconductor

TITLE

MARKETING OUTLINE - 16L CHIP SCALE BGA (4X4)
1.0MM PITCH, 1.41 THICK, 2 LAYER

CHECKED BY:

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